

Welcome to O-leading

O-Leading strives to be your one stop solution partner in EMS supply chain, including PCB design , PCB fabrication and PCB assembly (PCBA).We provide some of the most advanced PCB technology, including HDI PCBs,multilayer PCBs, Rigid-Flexible PCBs.We can support from quick turn prototype to medium & mass Production. ([High quality pcb manufacturer](#))

In general, our global customers are very impressed with our services:Rapid response, competitive price and quality commitment.Providing more valuable technical service and overall solution is the way O-leading forward.

Looking to the future, O-leading will concentrate on the innovation and development of electronics manufacturing technology as always, and make persistent efforts on PCB & PCBA one-stop service to provide first-class services and create more value for our customers.

PLEASE CLICK THESE FOR MORE INFORMATION [led pcb board manufacturer](#)

Product Description

Place of Origin	Guang dong, China (Mainland)	Brand Name	O-Leading
Base Material	FR-4,,Aluminum	Copper Thickness	0.5oz-5oz
Min. Hole Size	0.2mm	Min. Line Width	0.2mm
Surface Finishing	immersion gold ,OSP,lead free HASL	Board Thickness	0.1-5mm
applicable to	led,mobile phone,air conditioners,washing machines	character	Industrial Control pcb
certificates	ISO9001,UL,RoHS,SGS	Q/CTN	10PCS-100PCS
weight	0.01kg -5kg	MOQ	10pcs
Model Number	power bank pcb assembly pcba manufacturer	Min. Line Spacing	0.2mm
color	blue ,red ,green,black,yellow	price	\$0.1-\$10
design type	client requirement	size	0.01m3-10m3

Production Capability

16 years professional OEM pcb board manufacture

item	2014		2015~2016		2017~2018	
	Volume	Sample	Volume	Sample	Volume	Sample
Layer count	32	42	38	44	42	48
Min Line/space (μm)	50/50	40/45	40/45	40/40	35/40	35/35
Min drill hole diameter (mm)	0.15	0.10	0.15	0.10	0.15	0.10
Aspect ratio of PTH	14:1	16:1	16:1	18:1	18:1	20:1
N+C+N	4+C+4	5+C+5	5+C+5	6+C+6	5+C+5	6+C+6

Any layer interconnection	5+2+5	6+2+6	5+2+5	6+2+6	5+2+5	6+2+6
Plate filling via	YES	--	YES	--	YES	--
Min. core thickness (exclude copper) (µm)	50	40	40	30	40	30
Min. Laser Drill diameter (µm)	75	65	65	50	50	40
Via on buried hole/stacked via	YES	--	YES	--	YES	--
Material	FR4, Megtron, Nelco, Rogers, Heavy Copper, etc.					
Embedded capacitor PCB	YES	--	YES	--	YES	--
Surface Process	Lead-free HASL, ENIG, OSP, Immersion silver, Immersion tin, Flash gold, Gold finger plating, Selective hard gold plating, Peelable solder mask, Carbon ink					







www.o-leading.com

Our Team



Factory PCB



Automatic vacuum press machine



Drilling Machine



Pattern Plating Machine



Scrubbing Machine



Developing Machine



Routing Machine



High-speed flying probe machine



E-test Machine

Factory SMT



Certifications





No. SZXEC1900530401

Date: 30 Mar 2019

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O-LEADING SUPPLY CHAIN (HK) CO., LIMITED

1313, FLOOR 13, FORTUNE BUILDING, DANSHUI TOWN, HUIYANG DISTRICT, HUIZHOU, GUANGDONG, CHINA

The following sample(s) was/were submitted and identified on behalf of the clients as : OSP

SGS Job No. : RP19-005089 - SZ

Date of Sample Received : 22 Mar 2019

Testing Period : 22 Mar 2019 - 30 Mar 2019

Test Requested : Selected test(s) as requested by client.

Test Method : Please refer to next page(s).

Test Results : Please refer to next page(s).

Conclusion : Based on the performed tests on submitted sample(s), the results of Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBBs), Polybrominated diphenyl ethers (PBDEs) and Phthalates such as Bis(2-ethylhexyl) phthalate (DEHP), Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP), and Diisobutyl phthalate (DIBP) comply with the limits as set by RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU.

Signed for and on behalf of
SGS-CSTC Standards Technical Services Co., Ltd. Shenzhen Branch

Tina Fan
Approved Signatory



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No. SZXEC1900530401

Date: 30 Mar 2019

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Test Results :

Test Part Description:

Specimen No.	SGS Sample ID	Description
SN1	SZX19-005304.001	Green™PCB

Remarks :

(1) $1 \text{ mg/kg} = 1 \text{ ppm} = 0.0001\%$

(2) MDL = Method Detection Limit

(3) ND = Not Detected (< MDL)

(4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method : With reference to IEC 62321-4:2013+A1:2017, IEC62321-5:2013, IEC62321-7-2:2017, IEC 62321-6:2015 and IEC62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Test Item(s)	Limit	Unit	MDL	Q27
Cadmium (Cd)	100	mg/kg	2	ND
Lead (Pb)	1,000	mg/kg	2	8
Mercury (Hg)	1,000	mg/kg	2	ND
Hexavalent Chromium (Cr(VI))	1,000	mg/kg	8	ND
Sum of PBBs	1,000	mg/kg	-	ND
Monobromobiphenyl	-	mg/kg	5	ND
Dibromobiphenyl	-	mg/kg	5	ND
Tri bromobiphenyl	-	mg/kg	5	ND
Tetrabromobiphenyl	-	mg/kg	5	ND
Pentabromobiphenyl	-	mg/kg	5	ND
Hexabromobiphenyl	-	mg/kg	5	ND
Heptabromobiphenyl	-	mg/kg	5	ND
Octabromobiphenyl	-	mg/kg	5	ND
Nonabromobiphenyl	-	mg/kg	5	ND
Decabromobiphenyl	-	mg/kg	5	ND
Sum of PBDEs	1,000	mg/kg	-	ND
Monobromodiphenyl ether	-	mg/kg	5	ND
Dibromodiphenyl ether	-	mg/kg	5	ND
Tri bromodiphenyl ether	-	mg/kg	5	ND
Tetrabromodiphenyl ether	-	mg/kg	5	ND
Pentabromodiphenyl ether	-	mg/kg	5	ND

[illegible]

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ZPMV2.E490354 - WIRING, PRINTED - COMPONENT

Wiring, Printed - Component

See General Information for Wiring, Printed - Component

O-LEADING SUPPLY CHAIN (HK) CO LTD

E490354

ROOM 1205, 12/F
TAI SANG BANK BLDG
130-132 DES VOEUS ROAD
CENTRAL, HONG KONG

Type	Cond Width		Cond Thk mic(mil)	SS/ DS/ DSO	Max		Max		Meets UL796 Class	C T DSR	I
	Min	Min			Area	Solder	Oper	Flame			
	mm(in)	mm(in)			Diam	Limits	Temp	Class			
Multilayer (mass laminate) printed wiring boards.											
O-LEADING-401	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	12.7 (0.5)	260	10	130	V-0	-	-
O-LEADING-407	0.08 (0.003)	0.2 (0.008)	17 (0.67)	DS	9.7 (0.4)	260	10	130	V-0	All	-
Multilayer printed wiring boards.											
O-LEADING-408	0.125 (0.005)	0.125 (0.005)	12 (0.47) Int:136	DS	50.8 (2.0)	280	20	130	V-0	All	*
Single layer printed wiring boards.											
O-LEADING-002	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	105	V-0	All	-
O-LEADING-003	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	130	V-0	▲	-
O-LEADING-033	0.15 (0.006)	0.3 (0.012)	34 (1.34)	SS	25.4 (1.0)	260	10	120	V-0	All	-
O-LEADING-205	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING-206	0.15 (0.006)	0.33 (0.013)	17 (0.67)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING-D01	0.14 (0.006)	0.15 (0.006)	33 (1.30)	DS	25.4 (1.0)	260	10	130	V-0	All	*
O-LEADING-S01	0.25 (0.010)	0.25 (0.010)	17 (0.67)	SS	25.4 (1.0)	260	4	130	V-0	All	*

WIRING, PRINTED - COMPONENT | UL Product iQ

O-LEADING-S02	0.2 (0.008)	0.2 (0.008)	17 (0.67)	SS	25.4 (1.0)	260	4	130	HB	▲
O-LEADING-S03	0.25 (0.010)	0.25 (0.010)	34 (1.34)	SS	25.4 (1.0)	260	4	130	V-0	All

* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.

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Packaging & Delivery

Shipping service



Quick Turn Lead Time		
Layer Count:	Lead Tim	Special Requirement
1L/2L	2-3days	24 Hours,48 Hours
4L	3-4days	48 Hours
6L	4-5days	72 Hours
8L	5-6days	NA
10L	6-7days	NA
12L	7-8days	NA
14L	8-9days	NA

Standard Lead Time		
Layer Count:	Sample Lead Time	Volume order lead time
2L	4 days	10 days
4L	5 days	11 days
6L	6 days	12 days
8L	8 days	14 days
10L	10 days	16 days
12L	12 days	18 days
14L	14 days	20 days
16-32L	18 days	24 days

Process Capability

PCB Production Capabilities

Layer Count: 1Layer-32Layer

Finished copper thickness□ 1/3oz-12oz

Min Line width/spacing internal□ 3.0mil/3.0mil

Min Line width/spacing external: 4.0mil/4.0mil

Max Aspect Ratio: 10:1

Board thickness□ 0.2mm-5.0mm

Max Panel size(inches): 635*1500mm

Minimum Drilled Hole Size: 4mil

Plated Hole Tolerance: +/-3mil

Blind/Buried Vias (All Types): YES

Via Fill(Conductive,Non-Conductive): YES

Base Material: FR-4,FR-4high Tg,Halogen free material,Rogers,Aluminium base,Polyimide,
Heavy Copper

Surface finishes: HASL,OSP,ENIG,HAL-LF,Immersion silver,Immersion Tin,Gold fingers,Carbon ink

SMT Production Capabilities

PCB Material: FR-4,CEM-1,CEM-3,Aluminum-based board

Max PCB size: 510x460mm

Min PCB size□50x50mm

PCB Thickness□0.5mm-4.5mm

Board thickness□0.5-4mm

Min Components size: 0201

Standard chip size component: 0603 and larger

Component max height□15mm

Min lead pitch: 0.3mm

Min BGA ball pitch:0.4mm

Placement precision: +/-0.03mm